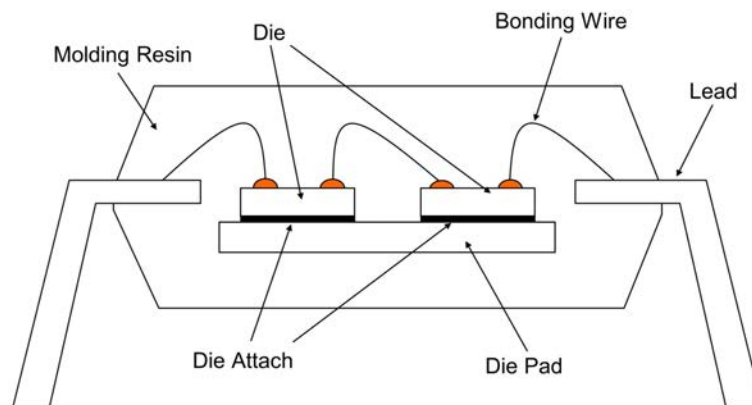


1. Package Information

| | |
|--------------------|----------|
| Package Name | DIP7K |
| Type | DIP |
| Pin Count | 7 |
| Package Weight [g] | 0.5 |
| Lead Finish | Pure Tin |
| MSL | - |

2. Package Structure



3. Packing Specification

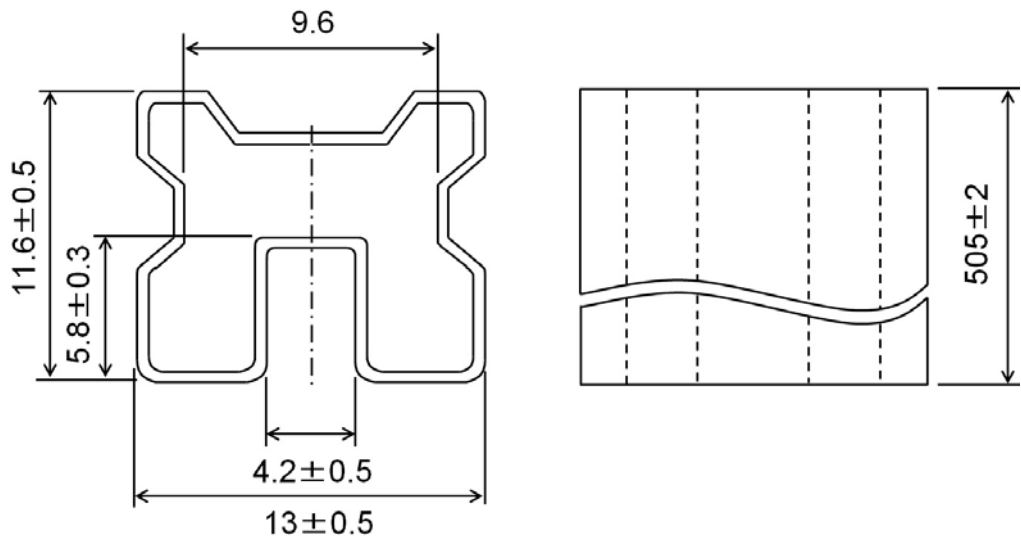
3.1 Packing form, Quantity

| | | |
|------------------|-------|------|
| Packing Form | | Tube |
| Packing Quantity | [pcs] | 50 |

3.2 Use material

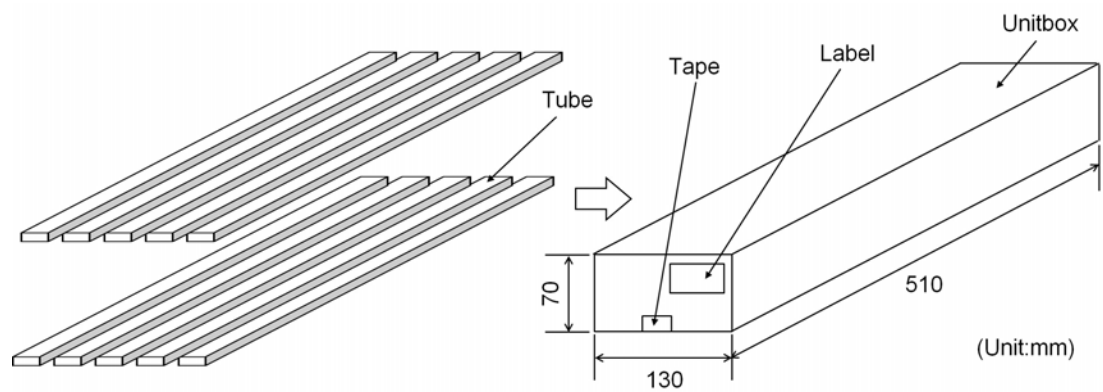
| Item | Material |
|--------------|-----------|
| Tube | PC |
| Stopper | TPE |
| Unit box | Cardboard |
| Shipping box | Cardboard |

3.3 Tube Specification
3.3.1 Tube Dimension

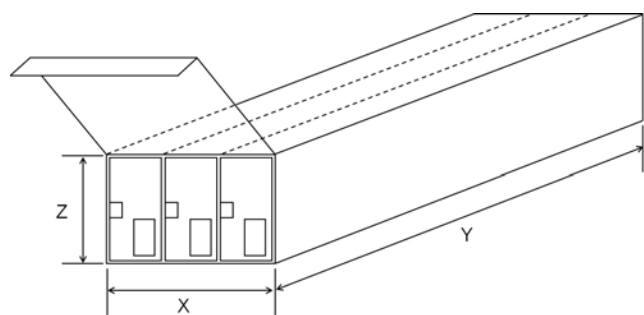


(unit:mm)

3.4 Packing Method
40 tube(s) or less per unit box



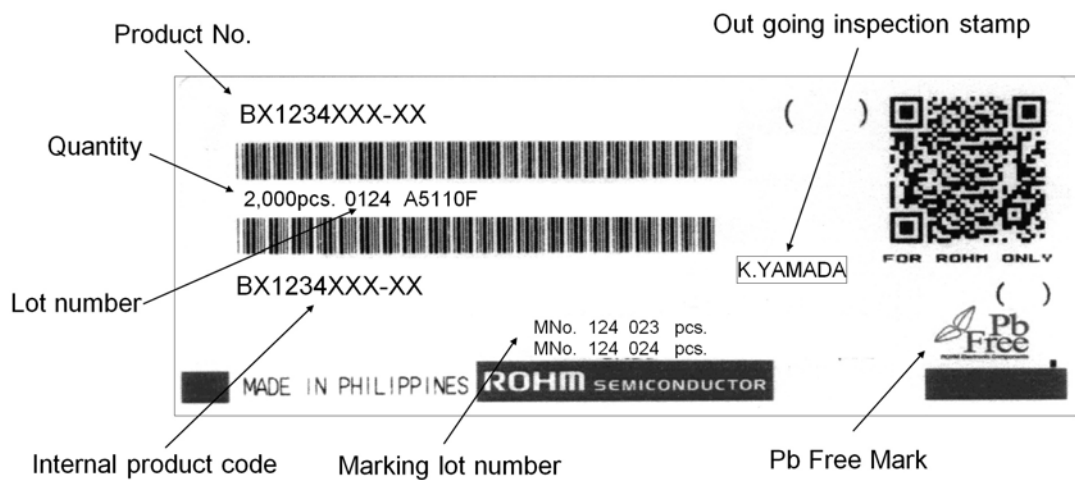
3.9 Packing Style
3 unit boxes or less per shipping box



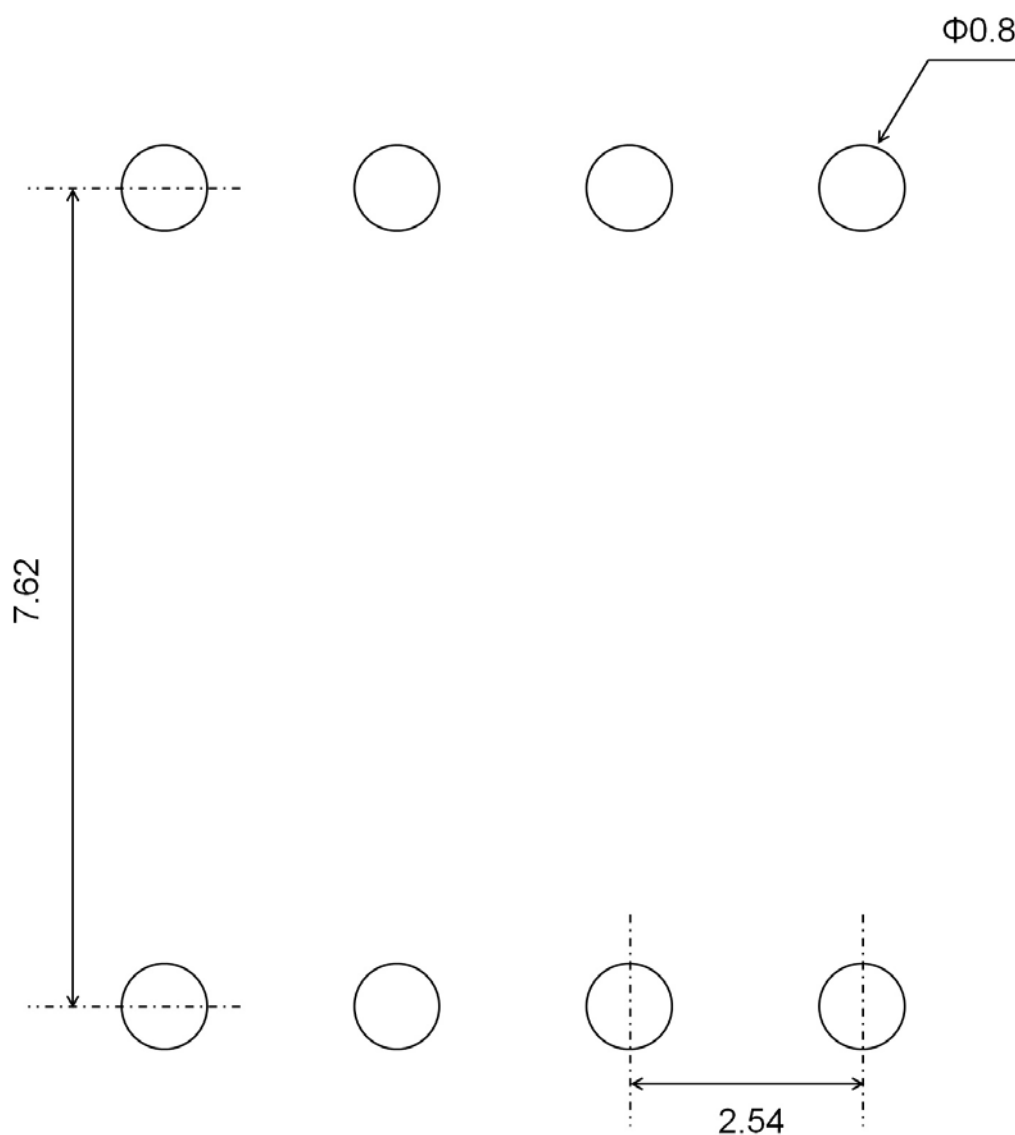
(unit:mm)

| Shipping Box Dimension | |
|------------------------|-----|
| X | 230 |
| Y | 579 |
| Z | 136 |

3.10 Label Specification



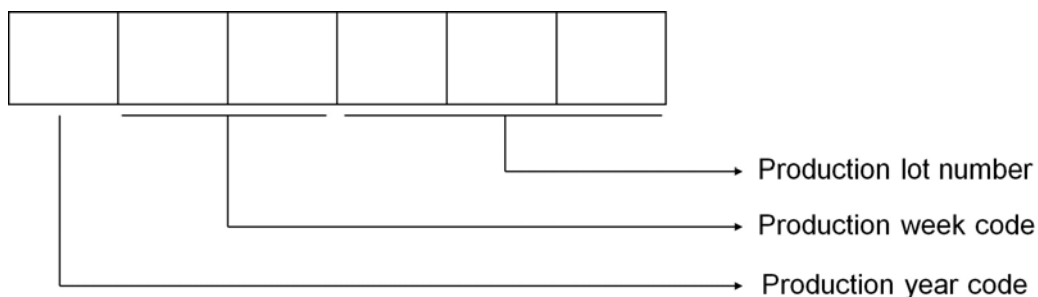
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

| | Min. | Max. | Unit |
|-------------|------|------|------|
| Temperature | 5 | 30 | °C |
| Humidity | 40 | 70 | % RH |

6.2 Storage period

| | Min. | Max. | Unit |
|----------------|------|------|------|
| Storage period | - | 1 | year |

7. Soldering conditions

7.1 Recommended condition for wave soldering

| | | |
|------------------------|---|------------------|
| Preheating temperature | : | 120 °C to 150 °C |
| Preheating time | : | 60 s MAX |
| Soldering temperature | : | 260 °C ± 3 °C |
| Soldering time | : | 12 s MAX |

Notes for wave soldering

- (1) Soldering time is provided for total soldering time in case of dual wave soldering.
- (2) Do not use other soldering methods with wave soldering.
- (3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (4) Optimize soldering condition to prevent solder bridging.

7.2 Recommended condition for solder iron

| | | |
|-------------------------|---|----------------|
| Solder iron temperature | : | 380 °C or less |
| Mounting time | : | 4 s or less |

Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
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- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
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